

LN11WP23

Round Type

φ5.0 mm

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

• Red

Parameter	Symbol	Rating	Unit
Power dissipation	P_D	70	mW
Forward current	I_F	25	mA
Pulse forward current *	I_{FP}	150	mA
Reverse voltage	V_R	4	V
Operating ambient temperature	T_{opr}	-25 to +85	°C
Storage temperature	T_{stg}	-30 to +100	°C

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

■ Lighting Color

- Red
- Yellow Green

• Yellow Green

Parameter	Symbol	Rating	Unit
Power dissipation	P_D	90	mW
Forward current	I_F	30	mA
Pulse forward current *	I_{FP}	150	mA
Reverse voltage	V_R	4	V
Operating ambient temperature	T_{opr}	-25 to +85	°C
Storage temperature	T_{stg}	-30 to +100	°C

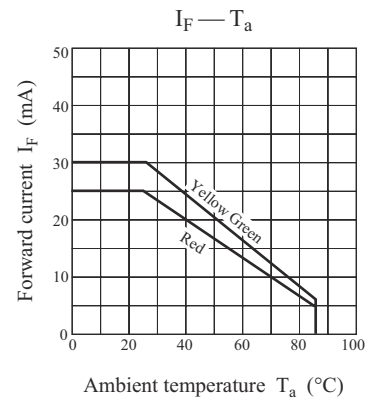
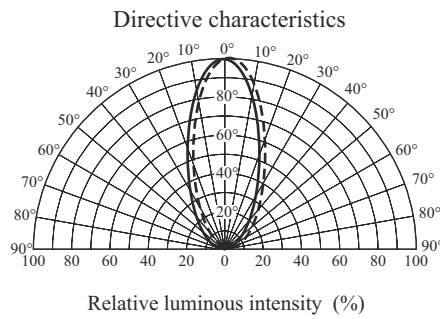
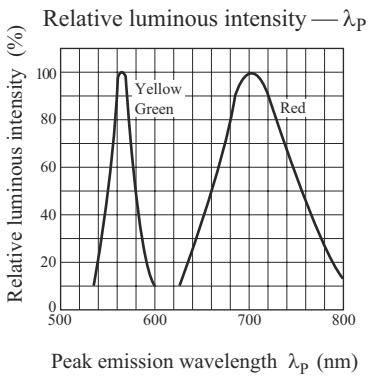
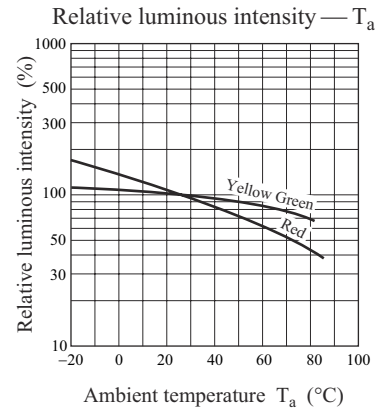
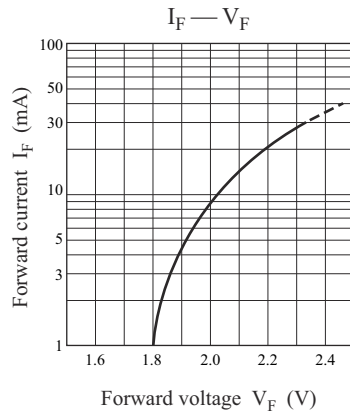
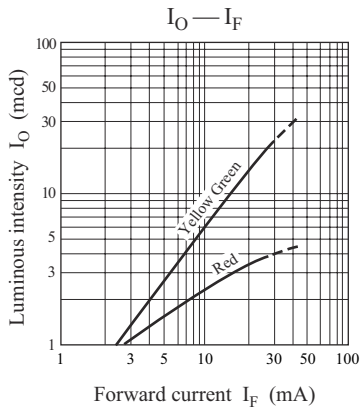
Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.■ Electro-Optical Characteristics $T_a = 25^\circ\text{C}$

• Red

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity	I_O		1.0	3.0		mcd
Reverse current	I_R	$V_R = 4\text{ V}$			10	μA
Forward voltage	V_F	$I_F = 20\text{ mA}$		2.2	2.8	V
Peak emission wavelength	λ_p	$I_F = 20\text{ mA}$		700		nm
Spectral half band width	$\Delta\lambda$	$I_F = 20\text{ mA}$		100		nm

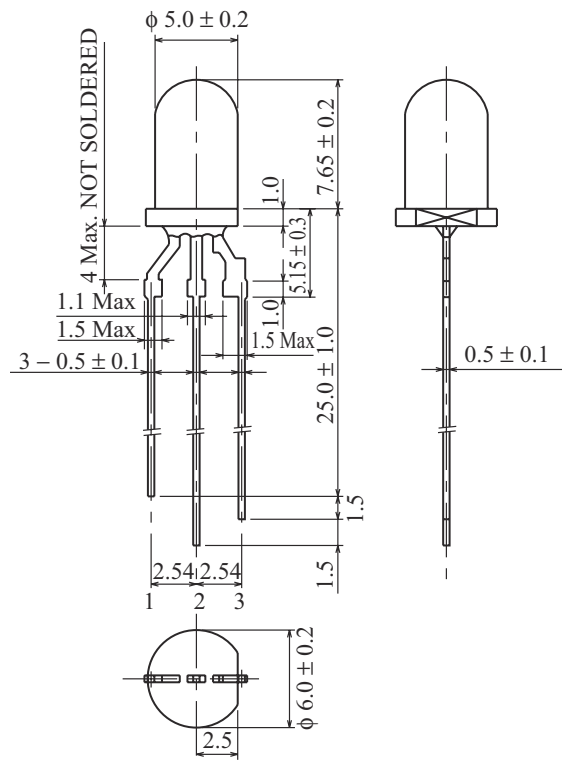
• Yellow Green

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity	I_O		3.0	15.0		mcd
Reverse current	I_R	$V_R = 4\text{ V}$			10	μA
Forward voltage	V_F	$I_F = 20\text{ mA}$		2.2	2.8	V
Peak emission wavelength	λ_p	$I_F = 20\text{ mA}$		565		nm
Spectral half band width	$\Delta\lambda$	$I_F = 20\text{ mA}$		30		nm



■ Package (Unit: mm)

LLXLTN3SH012



• Pin name

- 1: Anode (Yellow Green)
- 2: Cathode (Common)
- 3: Anode (Red)

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